<u>TOSHIBA</u>

TOSHIBA Power Transistor Module Silicon Epitaxial Type (Six Darlington Power Transistors in One)

MP6901

High Power Switching Applications

Hammer Drive, Pulse Motor Drive and Inductive Load Switching

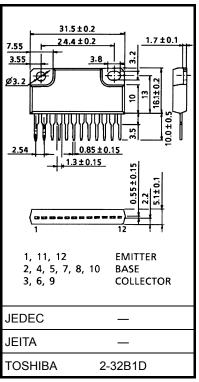
- Package with heat sink isolated to lead (SIP 12 pins)
- High collector power dissipation (6-device operation) : $P_T = 5 \text{ W} (Ta = 25^{\circ}\text{C})$
- High collector current: $IC (DC) = \pm 4 A (max)$
- High DC current gain: $h_{FE} = 2000 \text{ (min)} (V_{CE} = \pm 2 \text{ V}, I_C = \pm 1 \text{ A})$

Maximum Ratings (Ta = 25°C)

Characteristi	Symbol	Ra	Unit		
Characteristi	Symbol	NPN	PNP	Onit	
Collector-base voltage		V _{CBO}	100	-100	V
Collector-emitter voltage		V _{CEO}	80	-80	V
Emitter-base voltage		V _{EBO}	5	-5	V
Collector current		Ι _C	4	-4	А
	I _{CP}	6	-6	Α	
Continuous base current	Ι _Β	0.4	-0.4	А	
Collector power dissipation		Pc	3.0		W
(1-device operation)		۲C	3.0		vv
Collector power dissipation			5.0		W
(6-device operation)	Tc = 25°C	PT	2	5	vv
Isolation voltage	V _{Isol}	1000		V	
Junction temperature	Тj	150		°C	
Storage temperature ran	T _{stg}	-55 to 150		°C	

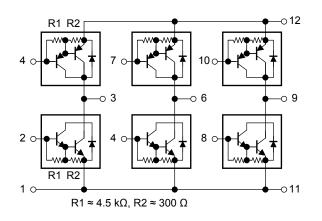
Industrial Applications



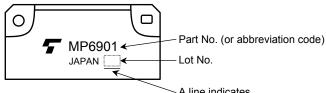


Weight: 6.0 g (typ.)

Array Configuration



Marking



A line indicates
 lead (Pb)-free package or
 lead (Pb)-free finish.

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance from junction to ambient	ΣR _{th (j-a)}	25	°C/W
(6-device operation, Ta = 25°C)			
Thermal resistance from junction to case	ΣR _{th (j-c)}	5.0	°C/W
(6device operation, Tc = 25°C)	,		
Maximum lead temperature for soldering purposes	ΤL	260	°C
(3.2 mm from case for 10 s)			

Electrical Characteristics (Ta = 25°C) (NPN transistor)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I _{CBO}	V _{CB} = 100 V, I _E = 0 A	_	—	20	μA
Collector cut-off cu	rrent	ICEO	V _{CE} = 80 V, I _B = 0 A	_	—	20	μA
Emitter cut-off curr	ent	I _{EBO}	V _{EB} = 5 V, I _C = 0 A	0.5	_	2.5	mA
Collector-base brea	akdown voltage	V (BR) CBO	I _C = 1 mA, I _E = 0 A	100	—	_	V
Collector-emitter b	reakdown voltage	V (BR) CEO	I _C = 10 mA, I _B = 0 A	80	_	_	V
DC ourrent goin		h _{FE (1)}	V _{CE} = 2 V, I _C = 1 A	2000	—	_	
DC current gain	h _{FE (2)}	V _{CE} = 2 V, I _C = 3 A	1000	_	_	—	
Saturation voltage	Collector-emitter	V _{CE (sat)}	I _C = 3 mA, I _B = 6 mA	_	—	1.5	v
	Base-emitter	V _{BE (sat)}	I _C = 3 mA, I _B = 6 mA	_	_	2.0	
Transition frequency		fT	V _{CE} = 2 V, I _C = 0.5 A	_	60	_	MHz
Collector output capacitance		C _{ob}	V _{CB} = 10 V, I _E = 0 A, f = 1 MHz	_	35	_	pF
Turn-on time Switching time Storage time Fall time	Turn-on time	ton	$\begin{array}{c} \text{Output} \\ \text{Input} \\ 20 \ \mu\text{s} \\ \text{Imput} \\ \text{Impu} \\ \text{Imput} \\ \text{Imput} \\ \text{Imput} \\ \text{Imput} \\ $	_	0.2	_	
	Storage time	^t stg		_	1.5	_	μs
	Fall time	t _f	$I_{B1} = -I_{B2} = 6$ mA, duty cycle ≤ 1%	_	0.6	_	

Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I _{FM}	—	_	_	4	А
Surge current	I _{FSM}	t = 1 s, 1 shot	_	_	6	А
Forward voltage	VF	I _F = 1 A, I _B = 0 A	_	_	2.0	V
Reverse recovery time	t _{rr}	I _F = 4 A, V _{BE} = −3 V, dI _F /dt = −50 A/µs	_	1.0	_	μs
Reverse recovery charge	Q _{rr}			8	_	μC

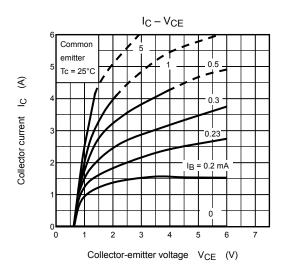
Electrical Characteristics (Ta = 25°C) (PNP transistor)

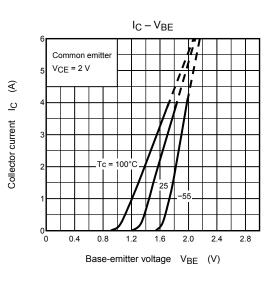
Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off cu	rrent	I _{CBO}	$V_{CB} = -100 \text{ V}, \text{ I}_{E} = 0 \text{ A}$	_	_	-20	μA
Collector cut-off cu	rrent	ICEO	V _{CE} = -80 V, I _B = 0 A	_	_	-20	μA
Emitter cut-off curr	ent	I _{EBO}	$V_{EB} = -5 V, I_C = 0 A$	-0.5	_	-2.5	mA
Collector-base brea	akdown voltage	V (BR) CBO	I _C = -1 mA, I _E = 0 A	-100	_	_	V
Collector-emitter b	reakdown voltage	V (BR) CEO	I _C = -10 mA, I _B = 0 A	-80	_	_	V
		h _{FE (1)}	$V_{CE} = -2 V, I_C = -1 A$	2000	_	_	
DC current gain	h _{FE (2)}	$V_{CE} = -2 V, I_C = -3 A$	1000	_	_		
Saturation voltage	Collector-emitter	V _{CE (sat)}	$I_{\rm C} = -3 \text{ A}, I_{\rm B} = -6 \text{ mA}$	_	_	-1.5	- V
	Base-emitter	V _{BE (sat)}	I _C = -3 A, I _B = -6 mA	_	_	-2.0	
Transition frequency		f _T	$V_{CE} = -2 V, I_C = -0.5 A$	_	40	_	MHz
Collector output capacitance		C _{ob}	V _{CB} = -10 V, I _E = 0 A, f = 1 MHz	_	60	_	pF
Switching time Stor	Turn-on time	t _{on}	Dutput	_	0.15	_	
	Storage time	t _{stg}		_	0.80	_	μs
	Fall time	t _f	V_{CC} = −30 V −I _{B1} = I _{B2} = 6 mA, duty cycle ≤ 1%	_	0.40	_	

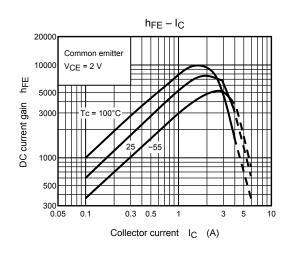
Emitter-Collector Diode Ratings and Characteristics (Ta = 25°C)

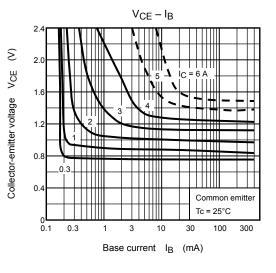
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward current	I _{FM}	—	-	_	4	А
Surge current	I _{FSM}	t = 1 s, 1 shot	_	_	6	А
Forward voltage	VF	I _F = 1 A, I _B = 0 A	_	_	2.0	V
Reverse recovery time	t _{rr}	I _F = 4 A, V _{BE} = 3 V, dI _F /dt = −50 A/µs	_	1.0	_	μs
Reverse recovery charge	Q _{rr}		_	8	_	μC

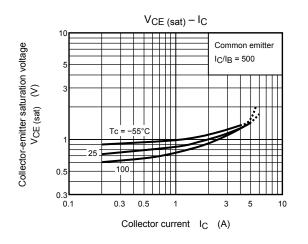
(NPN transistor)

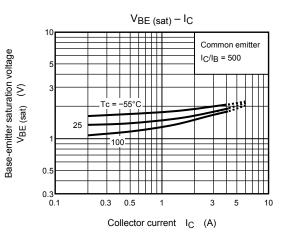




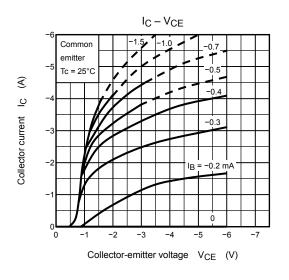


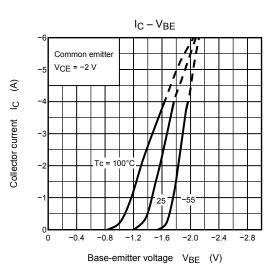


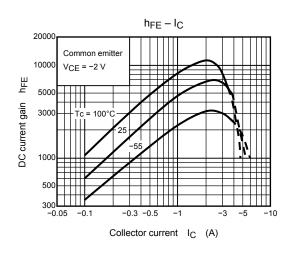


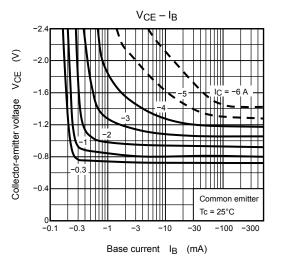


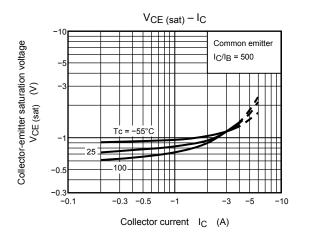
(PNP transistor)

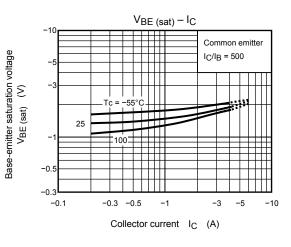


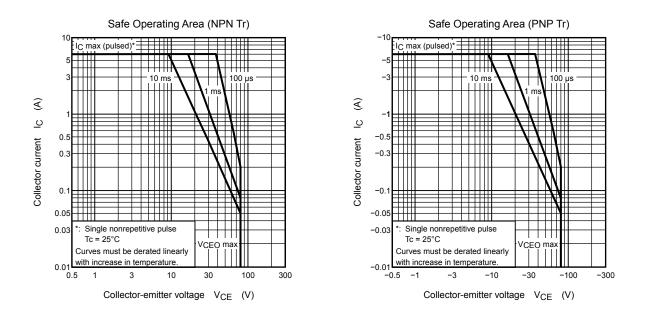


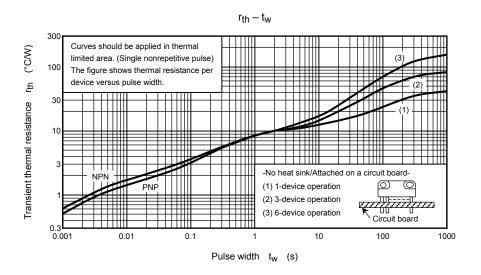


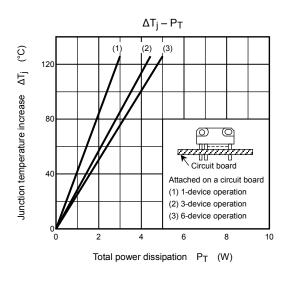


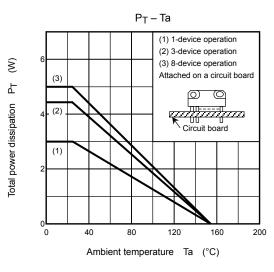












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